

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): In a probe device, an improved contact probe comprising:

- a first film having a first side and a second side;
- a plurality of wiring patterns formed on the first side of the first film;
- a second film having a first side and a second side, said first side of said second film formed on an opposite side of said plurality of wiring patterns from said first film, each wiring pattern having a front end portion projecting from the first and second films film so as to form contact pins;
- a first metal layer provided on the second side of said first film; and
- a second metal layer provided on the second side of the second film, said first metal layer coextensive with said second metal layer.

Claims 2-20 (Canceled).

Claim 21 (Previously Presented): The probe device recited in Claim 1 wherein said wiring patterns comprise nickel.

Claim 22 (Previously Presented): The probe device recited in Claim 21 wherein said wiring patterns are plated with gold.

Claim 23 (Previously Presented): The probe device recited in Claim 1 wherein said contact pins comprise nickel.

Claim 24 (Previously Presented): The probe device recited in Claim 23 wherein said contact pins are plated with gold.

Claim 25 (Currently Amended): The probe device recited in Claim 1 wherein said first metal layer comprises nickel.

Claim 26 (Currently Amended): The probe device recited in Claim 1 wherein said first metal layer comprises copper.

Claim 27 (Currently Amended): The probe device recited in Claim 26 wherein said first metal layer is plated with gold.

Claim 28 (Currently Amended): The probe device recited in Claim 1 wherein said first film comprises polyimide resin.

Claim 29 (Currently Amended): The probe device recited in Claim 1 wherein a thermal expansion coefficient of said first metal layer is the same as a thermal expansion coefficient of said contact pins.

Claim 30 (New): The probe device recited in Claim 1 wherein said second metal layer comprises nickel.

Claim 31 (New): The probe device recited in Claim 1 wherein said second metal layer comprises copper.

Claim 32 (New): The probe device recited in Claim 31 wherein said second metal layer is plated with gold.

Claim 33 (New): The probe device recited in Claim 1 wherein said second film comprises polyimide resin.

Claim 34 (New): The probe device recited in Claim 1 wherein a thermal expansion coefficient of said second metal layer is the same as a thermal expansion coefficient of said contact pins.